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Interested committees:

Title: Draft BS EN IEC 62047-37 Semiconductor devices - Micro-electromechanical devices. Part 37: Environmental test methods of MEMS piezoelectric thin films for sensor application.

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47F/324/CD

COMMITTEE DRAFT (CD)

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SUPERSEDES DOCUMENTS:

47F/316/NP, 47F/319A/RVN

IEC SC 47F : MICRO-ELECTROMECHANICAL SYSTEMS

SECRETARIAT:

Japan

SECRETARY:

Mr Takashi Mihara

OF INTEREST TO THE FOLLOWING COMMITTEES:

TC 49

PROPOSED HORIZONTAL STANDARD:

☐

Other TC/SCs are requested to indicate their interest, if any, in this CD to the secretary.

FUNCTIONS CONCERNED:

☐ EMC

☐ ENVIRONMENT

☐ QUALITY ASSURANCE

☐ SAFETY

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Recipients of this document are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

TITLE:

Semiconductor devices - Micro-electromechanical devices - Part 37: Environmental test methods of MEMS piezoelectric thin films for sensor application

NOTE FROM TC/SC OFFICERS:

This draft of CD was discussed and agreed at WG of Busan (2018-10-17)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –****Part 37: Environmental test methods of MEMS piezoelectric thin films for
sensor application****FOREWORD**

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International Standard IEC 62047-37 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47F/XX/FDIS	47F/XX/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

97 A list of all parts in the IEC62047 series, published under the general title *Semiconductor*
98 *devices – Micro-electromechanical devices*, can be found on the IEC website.

99 The committee has decided that the contents of this document will remain unchanged until the
100 stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to
101 the specific document. At this date, the document will be

- 102 • reconfirmed,
- 103 • withdrawn,
- 104 • replaced by a revised edition, or
- 105 • amended.

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